

Title (en)

Circuit board for hiding electronic components

Title (de)

Leiterplatte für das Verstecken von elektronischen Bauelementen

Title (fr)

Carte de circuits pour cacher des composants électroniques

Publication

EP 1701599 A1 20060913 (EN)

Application

EP 05005273 A 20050310

Priority

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Abstract (en)

The present invention is related to an assembly structure for hiding electronic components, that is, at least one containing hole penetrating through a PCB being set on a predetermined location of the PCB, circuits being arranged on at least one surface of a predetermined side edge of the containing hole, the containing hole being capable of reserving at least one electronic component (IC chip, resistance, capacitance or LED, etc.) so as to that at least one leg of the electronic component extending and connecting to the circuits of the surface for welding, the assembly structure for hiding electronic components is therefore formed.

IPC 8 full level

H05K 1/18 (2006.01)

CPC (source: EP)

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Citation (search report)

- [XY] US 6459593 B1 20021001 - KWONG HERMAN [CA]
- [XY] US 5386343 A 19950131 - PAO YI-HSIN [US]
- [XY] PATENT ABSTRACTS OF JAPAN vol. 014, no. 194 (E - 0919) 20 April 1990 (1990-04-20)
- [XY] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 11 28 November 1997 (1997-11-28)
- [XY] PATENT ABSTRACTS OF JAPAN vol. 014, no. 371 (E - 0963) 10 August 1990 (1990-08-10)

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